

Variable Capacitance Diode

Description

The 1T413 is a variable capacitance diode designed for the digital cellular phone VCO using a super-small-miniature flat package (SSVC).

Features

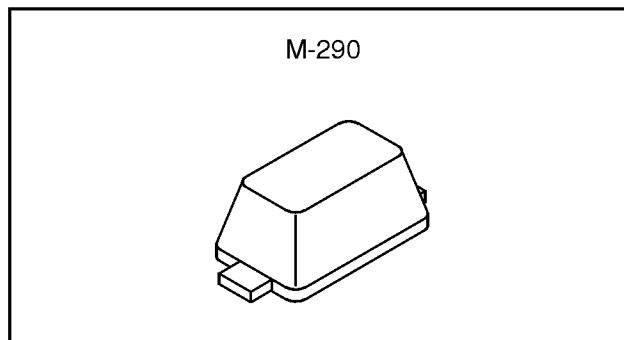
- Super-small-miniature flat package
- Low series resistance: 0.40 Ω Max. (f=470 MHz)
- Large capacitance ratio: 2.90 Typ. (C₁/C₄)
- Small leakage current: 10 nA Max. (V_R=15 V)

Applications

Digital cellular phone VCO

Structure

Silicon epitaxial planar type diode



Absolute Maximum Ratings (T_a=25 °C)

- | | | | |
|-------------------------|------------------|-------------|----|
| • Reverse voltage | V _R | 15 | V |
| • Operating temperature | T _{opr} | -20 to +75 | °C |
| • Storage temperature | T _{stg} | -65 to +150 | °C |

Electrical Characteristics

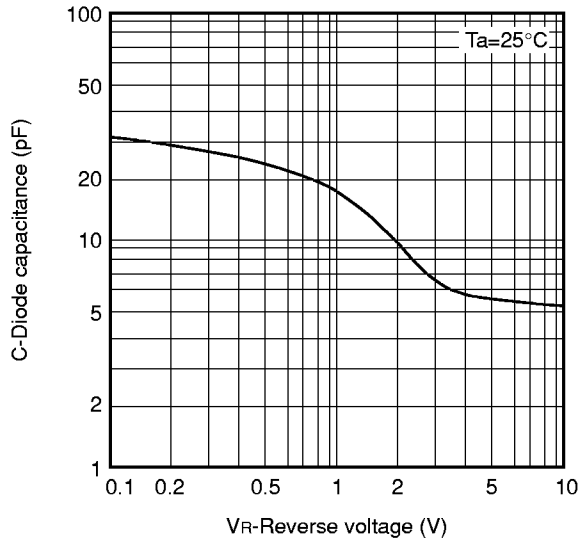
(T_a=25 °C)

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Reverse current	I _R	V _R =15 V			10.0	nA
Diode capacitance	C ₁	V _R =1 V, f=1 MHz	15.0		17.5	pF
	C ₄	V _R =4 V, f=1 MHz	5.1		6.1	pF
Capacitance ratio	C ₁ /C ₄		2.5	2.9		
Series resistance	r _s	V _R =1 V, f=470 MHz			0.40	Ω

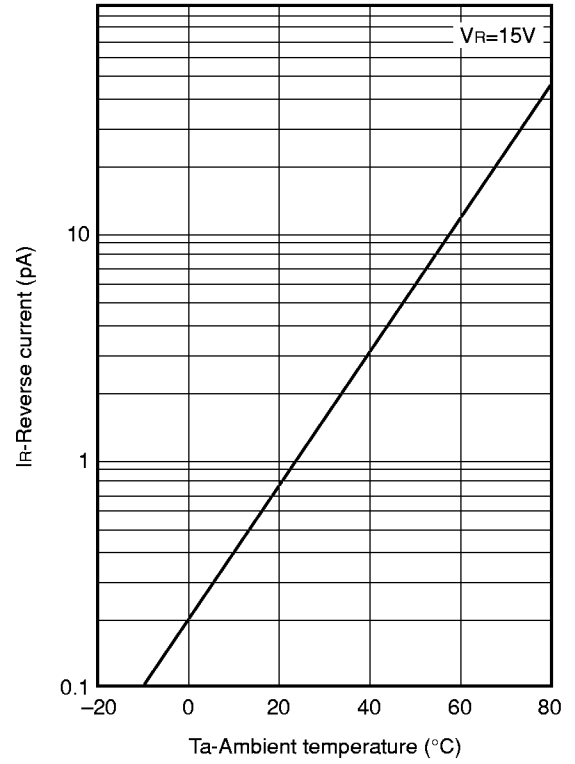
Sony reserves the right to change products and specifications without prior notice. This information does not convey any license by any implication or otherwise under any patents or other right. Application circuits shown, if any, are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits.

Example of Representative Characteristics

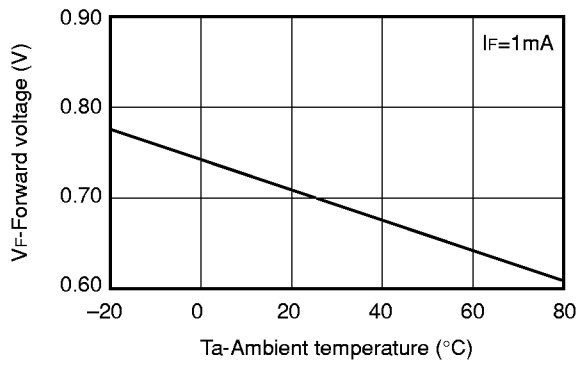
Diode capacitance vs. Reverse voltage



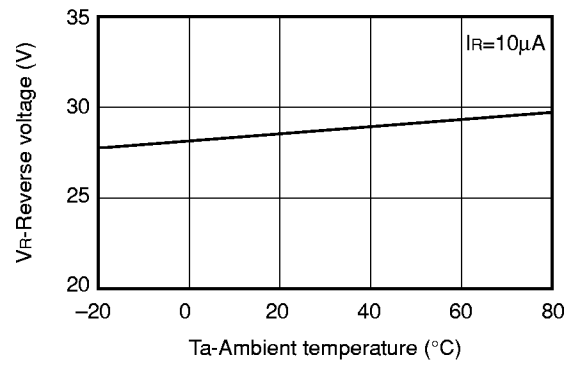
Reverse current vs. Ambient temperature



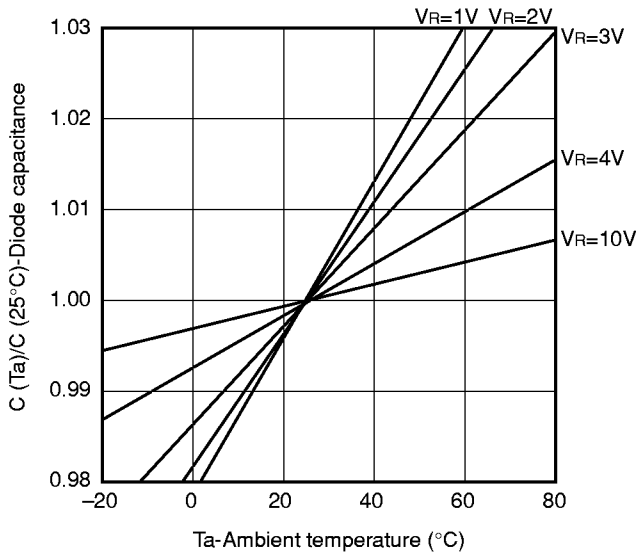
Forward voltage vs. Ambient temperature



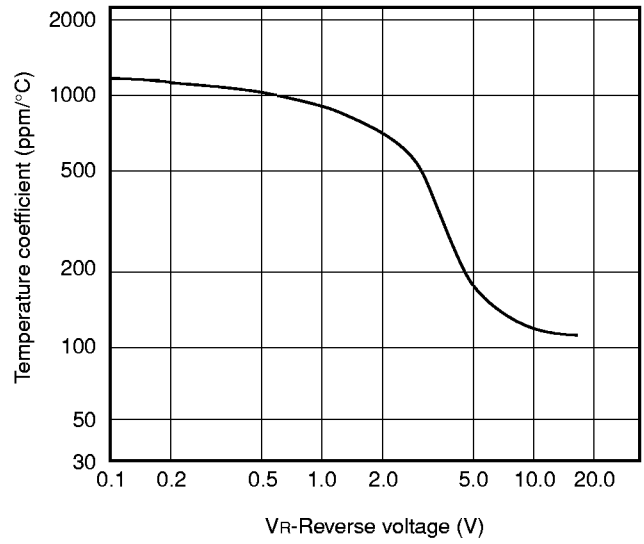
Reverse voltage vs. Ambient temperature



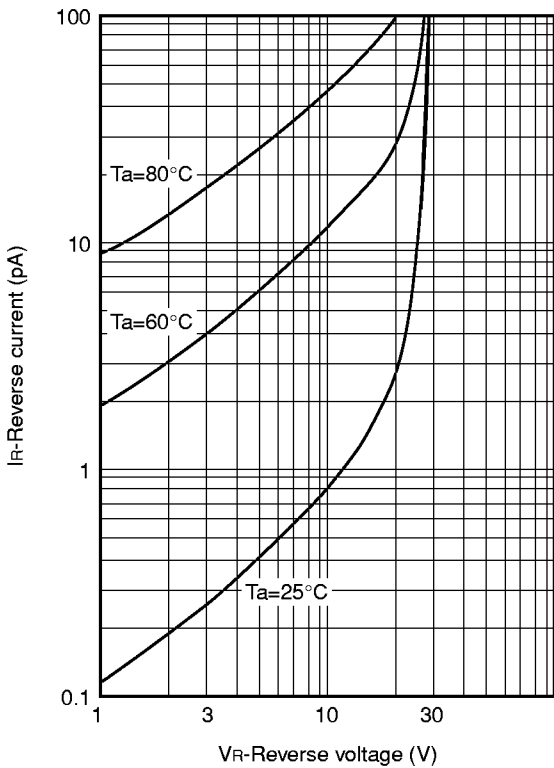
Diode capacitance vs. Ambient temperature



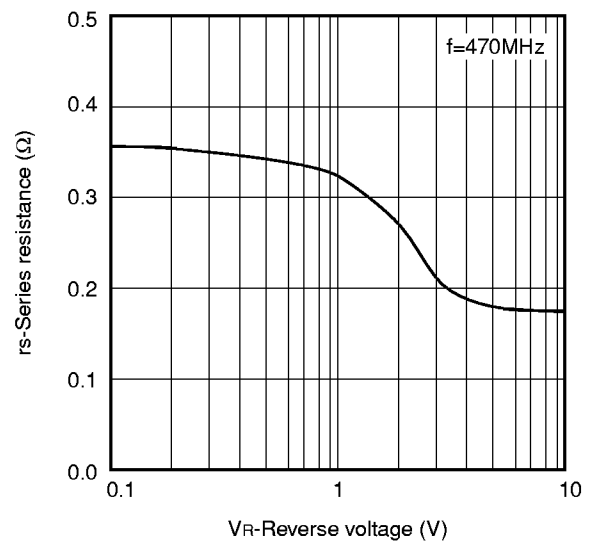
Temperature coefficient of diode capacitance



Reverse current vs. Reverse voltage

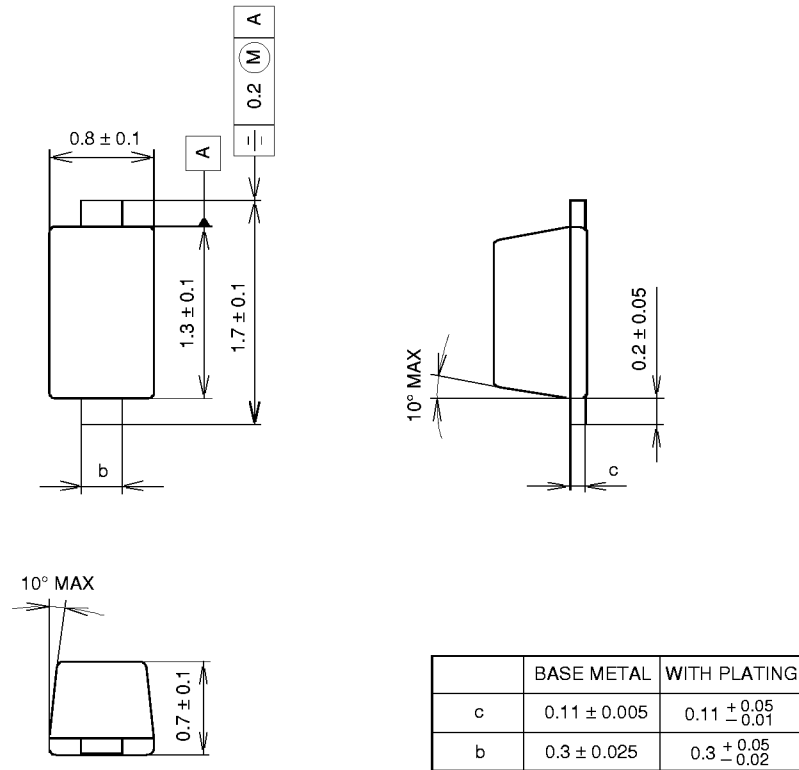


Series resistance vs. Reverse voltage



Package Outline Unit : mm

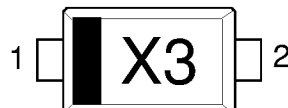
M-290



SONY CODE	M-290
EIAJ CODE	_____
JEDEC CODE	_____

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER
PACKAGE WEIGHT	0.002g

Mark



- 1 ⑆Cathode
- 2 ⑆Anode